What is claimed is:

1. A wiring board comprising:

a substrate; and

an interconnect pattern which is formed on the substrate and includes a land,

wherein a penetration hole which exposes the substrate is formed in the land, and

wherein the penetration hole is formed in a region along a periphery of the land.

2. The wiring board as defined in claim 1, wherein a planar shape of the land is approximately circular.

3. The wiring board as defined in claim 1, wherein the penetration hole is an elongated hole.

4. The wiring board as defined in claim 3, wherein the penetration hole is the elongated hole which is longer in a direction along the periphery of the land than in a direction intersecting the periphery of the land at right angles.

5. The wiring board as defined in claim 1, wherein a plurality of the penetration holes are formed in the land.

6. The wiring board as defined in claim 5, wherein the plurality of penetration holes are arranged in a region along the periphery of the land.

7. The wiring board as defined in claim 5, wherein the plurality of penetration holes are disposed so that distance between the adjacent penetration holes is

approximately the same.

8. The wiring board as defined in claim 1, further comprising:

a resist layer which is formed on a surface of the substrate on which the interconnect pattern is formed and includes an opening which exposes at least a part of the land.

9. The wiring board as defined in claim 8, wherein a planar shape of the opening of the resist layer is approximately circular.

10. The wiring board as defined in claim 8, wherein the resist layer covers at least a part of the penetration hole.

11. The wiring board as defined in claim 8,

wherein the resist layer covers the penetration hole, and

wherein part of an edge of the penetration hole is in contact with an edge of the opening of the resist layer.

12. The wiring board as defined in claim 1, which is formed as an interposer.

13. The wiring board as defined in claim 1, which is formed as a motherboard.

14. A semiconductor device comprising:

the wiring board as defined in claim 1, and

a semiconductor chip which is electrically connected with the interconnect pattern.

15. The semiconductor device as defined in claim 14, further comprising an external terminal formed on the land.

16. A circuit board on which the semiconductor device as defined in claim 14 is mounted.

17. Electronic equipment comprising the semiconductor device as defined in claim 14.

18. A method of manufacturing a wiring board, comprising:

forming an interconnect pattern including a land on a substrate,

wherein a penetration hole which exposes the substrate is formed in a region along a periphery of the land.

19. The method of manufacturing a wiring board as defined in claim 18, wherein the penetration hole is formed at the same time as the interconnect pattern.

20. The method of manufacturing a wiring board as defined in claim 18, wherein a plurality of the penetration holes are formed in the land.

21. The method of manufacturing a wiring board as defined in claim 18, further comprising:

forming a resist layer on a surface of the substrate, on which the interconnect pattern is formed, in a manner that the resist layer includes an opening which exposes at least a part of the land.